

●SOT-23 Power Dissipation

Power dissipation data for the SOT-23 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40×40mm (1600mm² in one side)

Copper (Cu) traces occupy 50% of the board area

In top and back faces

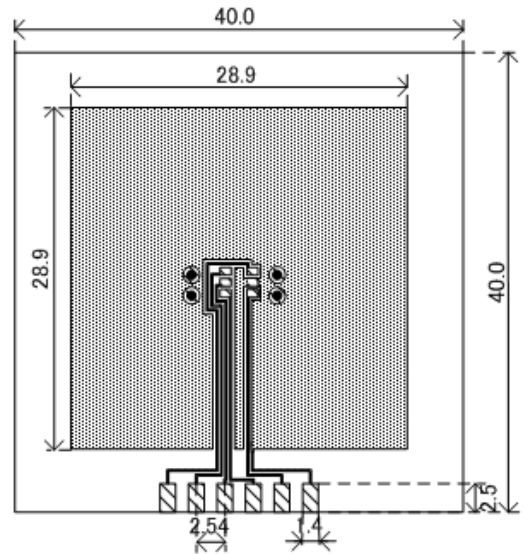
Package heat-sink is tied to the copper traces

(Board of SOT-26 is used)

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

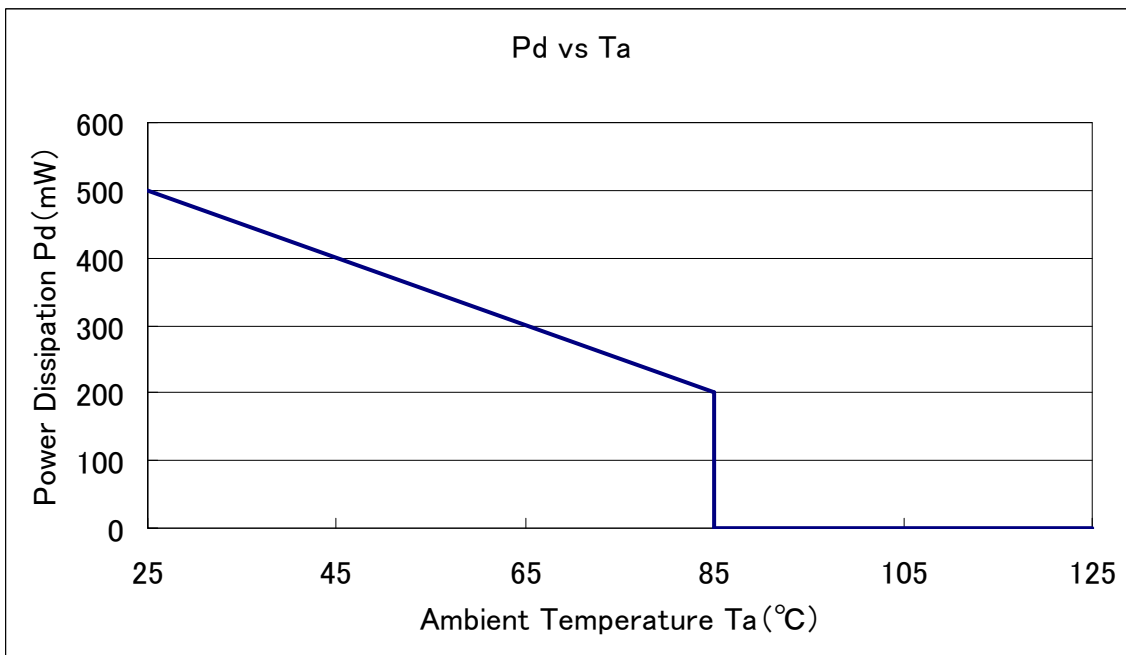
Through-hole : 4 x 0.8 Diameter



2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	200	



•SOT-23 Power Dissipation (Tj=150°C)

MOSFET DATA

Power dissipation data for the SOT-23 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

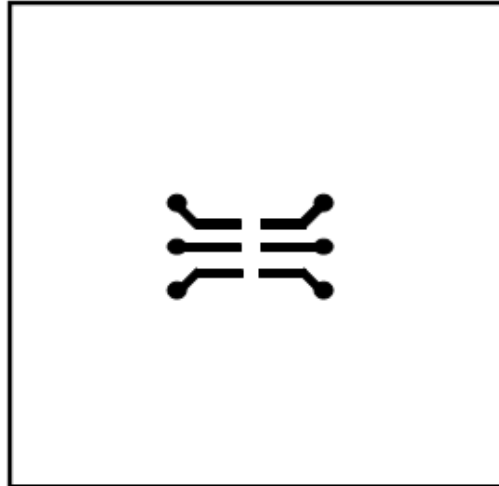
Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 250mm²

Material : Ceramic

Thickness : 0.8mm



2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	125.00
105	360	

